Topics and Abstracts:

Speaker	**Dr. Melissa GRUPEN-SHEMANSKY**
Company	**SEMI - FLEXTech**
Designation	**Chief Technology Officer, Flexible Electronics & Advanced Packaging**
Title of Presentation	**From Wellness to MedTech: The Role of Flexible, Printed Electronics in Wearables and Beyond**
Abstract	Despite significant media attention and venture capital funding, wearable technologies did not live up to the expectations set earlier this decade. Except for large established electronics manufacturers, many companies have struggled to introduce a sustained and successful wearable product. We will explore a brief history of wearable technologies, highlight winning and losing products, and discuss which application spaces are most promising. We will also examine the role of sensors and flexible hybrid electronics in the evolving landscape of wearables and moving beyond the form factors of smart watches and ear buds.

Biography

Dr. Grupen-Shemansky is the Chief Technology Officer at SEMI for flexible electronics and advanced packaging. She leads R&D consortia and the FlexTech governing and technical councils.

Melissa has over 25 years of experience in the semiconductor industry at various levels of management in research and development, manufacturing, business development, and technology strategy. Melissa began her career at Motorola, Semiconductor Products Sector and subsequently worked at Lucent, Bell Labs as Director of Interconnect and Design, and AMD/Spansion as Vice President of Packaging and Interconnect Technology. Prior to joining SEMI, Dr. Grupen-Shemansky was the Senior Vice President of Engineering for Advanced Nanotechnology Solutions, Inc, a startup in 3D ICs and cybersecurity.

Dr. Grupen-Shemansky holds both bachelor's and master's degrees in Chemical Engineering from Pennsylvania State University and a Ph.D. in Chemical Engineering from Arizona State University. She has received various corporate and educational awards, has seven issued patents, numerous technical publications, and is a contributing author to Failure-Free Integrated Circuit Packages.